

GI70L02

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	25V
RDS(ON)	9mΩ
ID	66A

Description

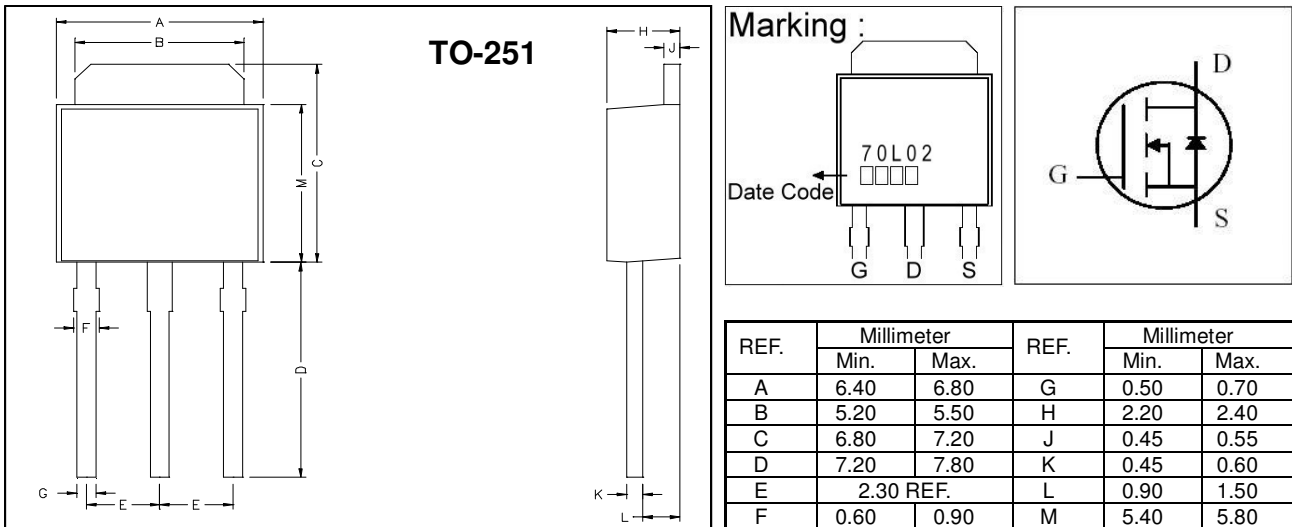
The GI70L02 provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The through-hole version (TO-251) is available for low-profile applications and suited for low voltage applications such as DC/DC converters.

Features

- *Simple Drive Requirement
- *Low Gate Charge
- *Fast Switching

Package Dimensions



Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	25	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=25^{\circ}C$	66	A
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=100^{\circ}C$	42	A
Pulsed Drain Current ¹	I_{DM}	210	A
Total Power Dissipation	$P_D @T_C=25^{\circ}C$	66	W
Linear Derating Factor		0.53	W/°C
Operating Junction and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-case Max.	$R_{thj-case}$	1.9	°C/W
Thermal Resistance Junction-ambient Max.	$R_{thj-amb}$	110	°C/W

Electrical Characteristics (T_j = 25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	25	-	-	V	$V_{GS}=0, I_D=250\mu A$
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_j$	-	0.037	-	V/°C	Reference to 25°C, $I_D=1mA$
Gate Threshold Voltage	$V_{GS(th)}$	1.0	-	3.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Forward Transconductance	g_{fs}	-	28	-	S	$V_{DS}=10V, I_D=33A$
Gate-Source Leakage Current	I_{GSS}	-	-	±100	nA	$V_{GS}= \pm 20V$
Drain-Source Leakage Current(T _j =25°C)	I_{DSS}	-	-	1	uA	$V_{DS}=25V, V_{GS}=0$
Drain-Source Leakage Current(T _j =150°C)		-	-	25	uA	$V_{DS}=20V, V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	9	mΩ	$V_{GS}=10V, I_D=33A$
		-	-	18		$V_{GS}=4.5V, I_D=20A$
Total Gate Charge ²	Q_g	-	23	-	nC	$I_D=33A$ $V_{DS}=20V$ $V_{GS}=5V$
Gate-Source Charge	Q_{gs}	-	3	-		
Gate-Drain ("Miller") Charge	Q_{gd}	-	17	-		
Turn-on Delay Time ²	$T_{d(on)}$	-	8.8	-	ns	$V_{DS}=15V$ $I_D=33A$ $V_{GS}=10V$ $R_G=3.3\Omega$ $R_D=0.45\Omega$
Rise Time	T_r	-	95	-		
Turn-off Delay Time	$T_{d(off)}$	-	24	-		
Fall Time	T_f	-	14	-		
Input Capacitance	C_{iss}	-	790	-	pF	$V_{GS}=0V$ $V_{DS}=25V$ $f=1.0MHz$
Output Capacitance	C_{oss}	-	475	-		
Reverse Transfer Capacitance	C_{rss}	-	195	-		

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	-	1.26	V	$I_S=66A, V_{GS}=0V, T_j=25^\circ C$
Continuous Source Current (Body Diode)	I_S	-	-	66	A	$V_D=V_G=0V, V_S=1.26V$
Pulsed Source Current (Body Diode) ¹	I_{SM}	-	-	210	A	

Drain-Source Avalanche Ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy ¹	E_{AS}	-	-	61	mJ	$V_{DD}=25V, I_D=35A,$ $L=100\mu H, V_{GS}=10V$
Avalanche Current	I_{AR}	-	-	35	A	

Notes: 1. Pulse width limited by safe operating area.

2. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Characteristics Curve

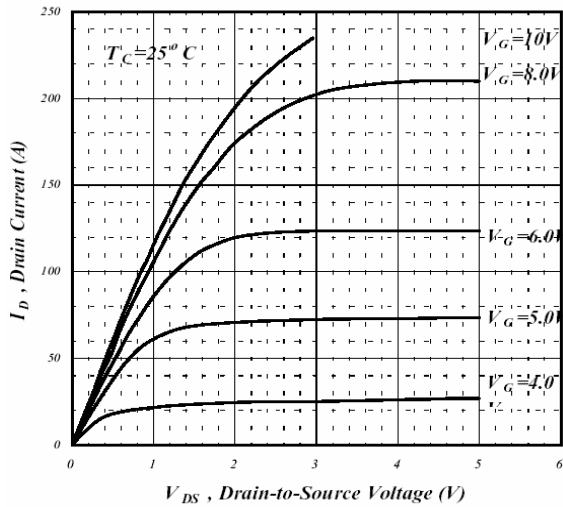


Fig 1. Typical Output Characteristics

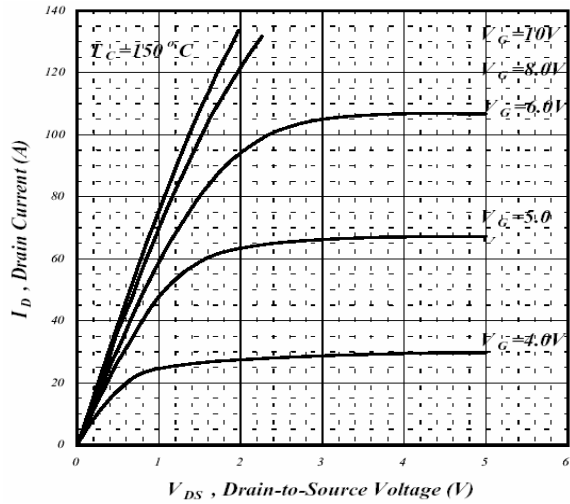


Fig 2. Typical Output Characteristics

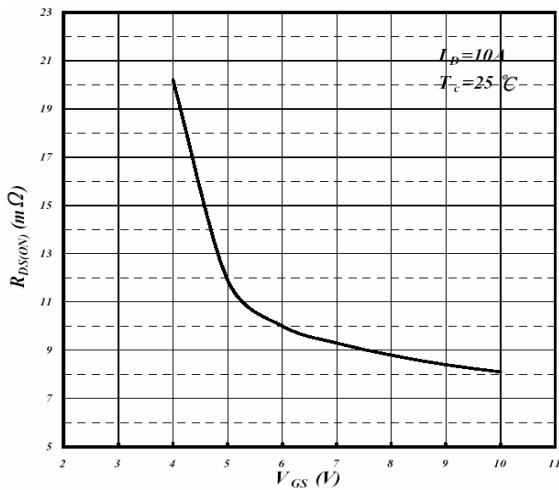


Fig 3. On-Resistance v.s. Gate Voltage

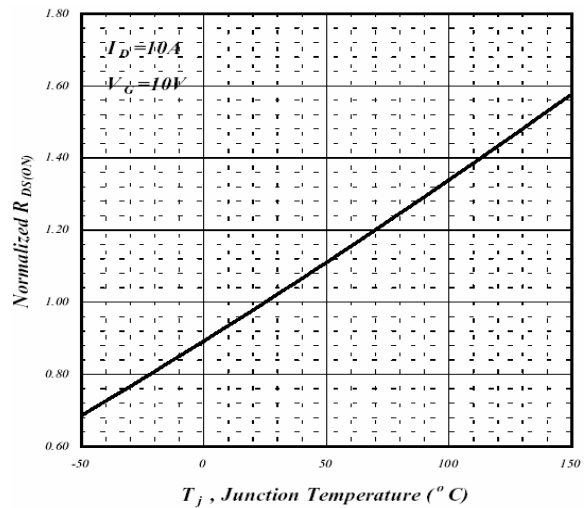


Fig 4. Normalized On-Resistance v.s. Junction Temperature

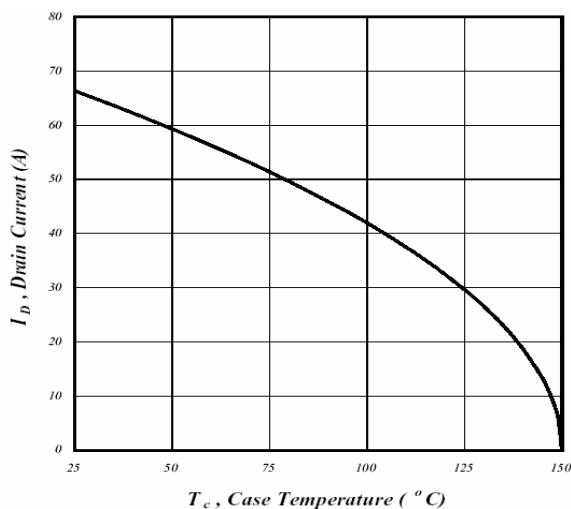


Fig 5. Maximum Drain Current v.s. Case Temperature

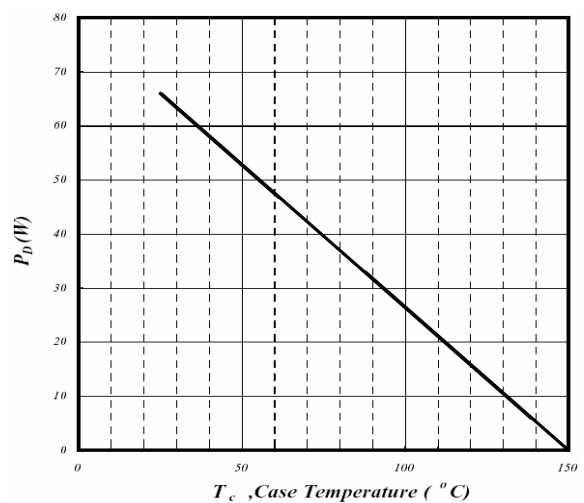


Fig 6. Type Power Dissipation

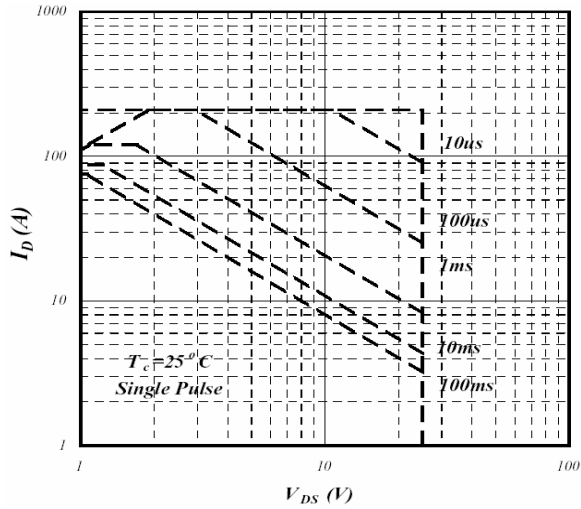


Fig 7. Maximum Safe Operating Area

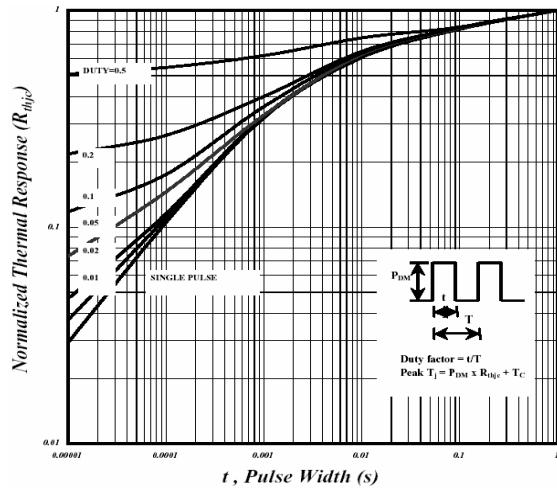


Fig 8. Effective Transient Thermal Impedance

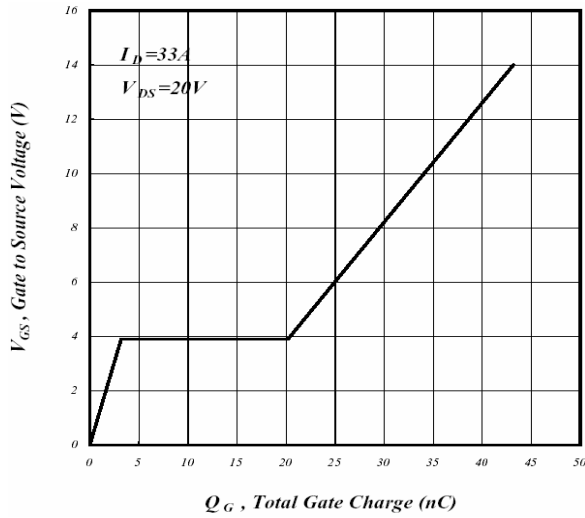


Fig 9. Gate Charge Characteristics

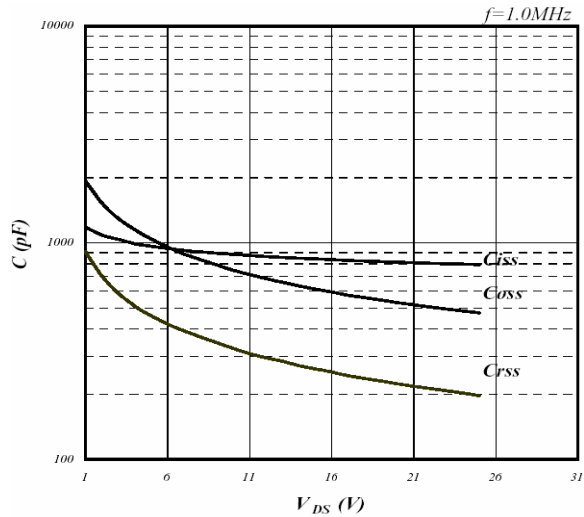


Fig 10. Typical Capacitance Characteristics

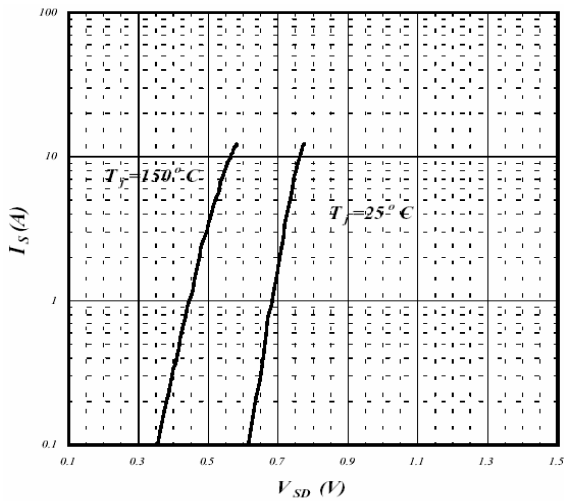


Fig 11. Forward Characteristics of Reverse Diode

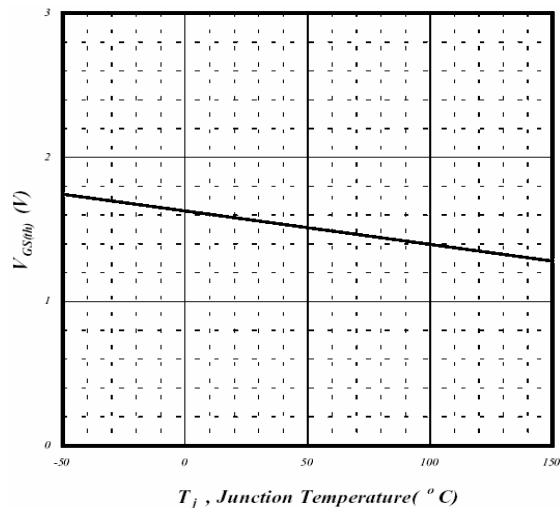


Fig 12. Gate Threshold Voltage v.s. Junction Temperature

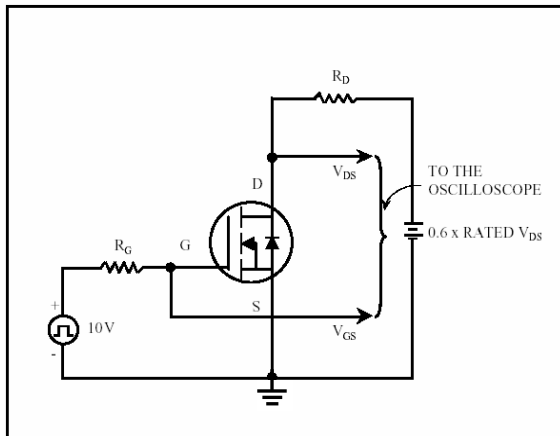


Fig 13. Switching Time Circuit

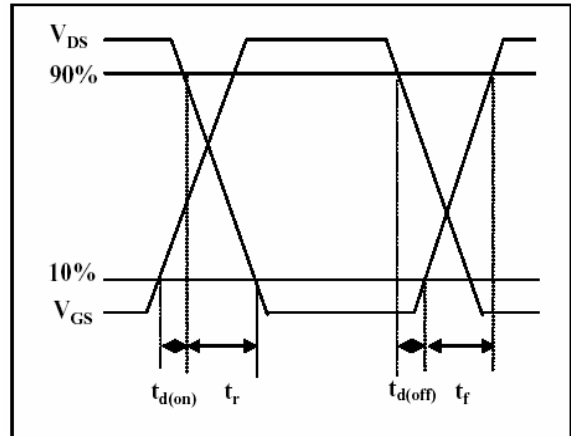


Fig 14. Switching Time Waveform

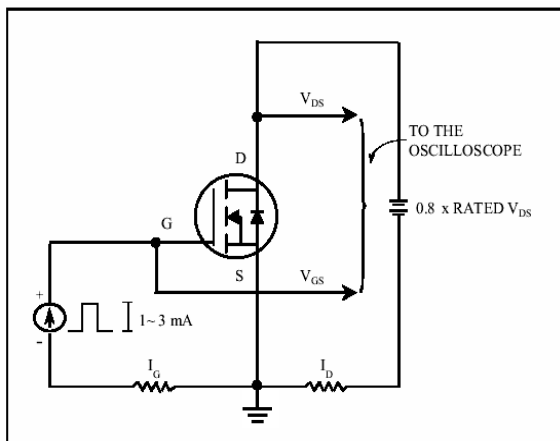


Fig 15. Gate Charge Circuit

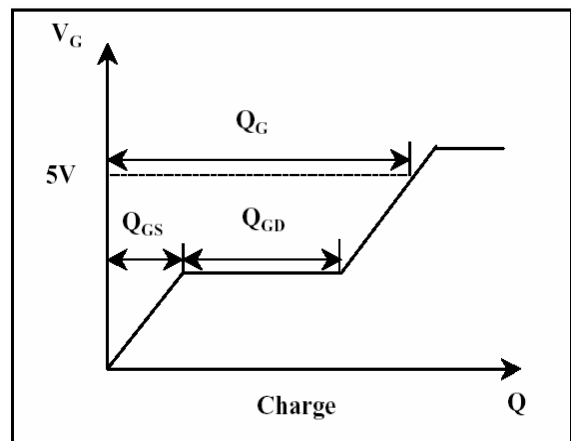


Fig 16. Gate Charge Waveform

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